



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-27
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH1R06A	HNSR*F62B81B	A	ZA41	2015-07-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	70.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMC	4.3-2.77-2	na	J bend	
Comment	Package: SMA			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HNSR*F62B81B					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.907	mg	supplier	die	Silicon (Si)	7440-21-3		0.793	mg	873755	11329
				supplier	metallization	Aluminium (Al)	7429-90-5		0.091	mg	100775	1300
				supplier	Passivation	Silicon Oxide	7631-86-9		0.008	mg	8859	114
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1107	14
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	5537	71
				supplier	polymer die coating	Probimide	proprietary		0.009	mg	9967	129
Leadframe	Copper & its alloys	27.007	mg	supplier	alloy	Copper (Cu)	7440-50-8		26.994	mg	999516	385629
				supplier	alloy	Zinc (Zn)	7440-66-6		0.001	mg	37	14
				supplier	alloy	Iron (Fe)	7439-89-6		0.003	mg	112	43
				supplier	alloy	Iron Phosphide (Fe2P)	1310-43-6		0.009	mg	335	129
Soft solder	Other organic materials	2.864	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.649	mg	924913	37843
				supplier	solder	Tin (Sn)	7440-31-5		0.144	mg	50175	2057
				supplier	solder	Silver (Ag)	7440-22-4		0.071	mg	24912	1014
encapsulation	Other organic materials	38.578	mg	supplier	mold compound	silica fused	7631-86-9		26.495	mg	686801	378500
				supplier	mold compound	silica quartz	14808-60-7		9.651	mg	250169	137871
				supplier	mold compound	phenolic resin	9003-35-4		2.316	mg	60035	33086
				supplier	mold compound	carbon black	1333-86-4		0.116	mg	2995	1657
connections coating	Solder	0.644	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.644	mg	1000000	9200